

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

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1. (Previously Presented) A device for cooling heat-generating electrical or electronic components having a non-uniform output profile, comprising a heat-conducting unit (1) and a heat-absorbing unit which contains a phase change material (4), wherein the phase change material is arranged in such a way that heat flow from the electrical or electronic component is preferentially to the heat-conducting unit (1) and a majority of heat flow to the phase change material from the electrical or electronic component occurs only when the temperature of the heat-conducting unit (1) exceeds phase change temperature  $T_{PC}$  of the phase change material.
2. (Original) The device according to claim 1, wherein the phase change material-containing unit (4) contains at least one cavity (6) into which the phase change material has been introduced, where the cavities (6) are formed by the heat-absorbing unit (4).
3. (Original) The device according to claim 1, wherein the phase change material containing unit (4) additionally contains a liquid/gaseous heat transfer medium (5).
4. (Original) The device according to claim 3, wherein the liquid/gaseous heat transfer medium (5) is a halogenated hydrocarbon.
5. (Original) The device according to claim 1, wherein a solid-solid phase change material is employed.

6. (Original) The device according to claim 1, wherein the phase change material is encapsulated.

7. (Original) The device according to claim 1, wherein the heat-conducting unit (1) has surface area-increasing structures.

8. (Original) The device according to claim 1, wherein the heat-conducting unit (1) has cooling fins.

9. (Previously Presented) A component (Z), comprising a cooling device according to claim 1, a heat-generating electronic component having non-uniform output (2), wherein units (1), (4) and component (2) are arranged in such a way that the heat flow between the heat-generating electronic component (2) and the heat-conducting unit (1) takes place in direct contact.

10. (Previously Presented) A component (Z) according to claim 9, wherein the heat-generating electronic component (2) is a computer CPU or memory chip.

11. (Original) A computer containing a component (Z) according to claim 9.

12. (Original) An electronic data processing system containing a device according to claim 1.

13. (Original) A mobile communication power switch or power circuit, a mobile telephone or fixed transmitter transmission circuit, an electromechanical actuator control circuit, a satellite communication or radar application high frequency circuit, or a domestic appliance or industrial electronic actuator or control unit, comprising a device according to claim 1.

14. (Currently Amended) A device for absorbing heat from a heat source, said device, comprising a heat sink and a heat absorbing component containing a phase change material, wherein heat flows from the heat source to the heat sink and flows from the heat sink to the heat absorbing component when the heat sink temperature exceeds the phase change temperature of the phase change material.

15. (Currently Amended) A device for absorbing heat from a heat source, said device, comprising a heat sink means and a heat absorbing means containing a phase change material, wherein heat flows from the heat source to the heat sink and flows from the heat sink means to the heat absorbing means when the heat sink temperature exceeds the phase change temperature of the phase change material.

16. (Currently Amended) A device for absorbing heat, comprising, in contact with a heat-generating electric or electronic component, a heat sink and a heat absorbing component containing a phase change material, wherein heat flows from the heat generating electric or electronic component to the heat sink, and from the heat sink to the heat absorbing

component when the heat sink temperature exceeds the phase change temperature of the phase change material.

17. (Previously Presented) A method for absorbing heat from a heat generating electronic or electric component, having a non-uniform output profile, comprising contacting said electric or electronic component with a heat sink and a heat absorbing component containing a phase change material, wherein heat flows from the heat sink to the heat absorbing component when the heat sink temperature exceeds the phase change temperature of the phase change material.

18. (Previously Presented) A method according to claim 17, wherein the heat sink temperature exceeds the phase change temperature of the phase change material at peak output of the electric or electronic component.

19. (Previously Presented) A method according to claim 17, wherein heat from the electric or electronic component flows directly to the heat sink.

20. (Previously Presented) A device according to claim 1, wherein the heat absorbing component is in direct contact with the electric or electronic component.

21. (Previously Presented) A device according to claim 14, wherein the heat absorbing component is in direct contact with the electric or electronic component.

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